ABSTRACT

The present invention provides a silica glass jig used in a process for manufacturing a semiconductor, characterized in that the silica glass jig has irregularities with center line average roughness Ra of from 0.1 to 20 μm on a part or all of a surface thereof and exhibits little change in a surface state on a slight surface layer etching treatment, whereby particles possibly contaminating a semiconductor device are not generated when the jig is used and treatment conditions need not be changed even if the jig is repeatedly used. Furthermore, the silica glass jig of the present invention can be easily manufactured by repeatedly applying a physical surface layer removal means and a chemical surface layer removal means onto a surface of a silica glass alternately twice or more.



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